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Maxim Integrated
MAX4814EECB+

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19-1056; Rev 0; 11/07

DVI/HDMI 2:4 Low-Frequency Fanout Switch

General Description

The MAX4814E high-definition multimedia interface (HDMI™) switch provides routing for low-frequency signals. The MAX4814E operates from a single +5.0V ±10% supply voltage and is ideal for connecting multiple HDMI sources to multiple loads.

The MAX4814E is a bidirectional 2:4 HDMI switch. Each switch consists of five single-pole/single-throw (SPST) channels. Two channels have a low 3Ω (typ) on-resistance to route +5V and drain (ground return), and three channels to route data. The device features a mode input to control the device through an I²C interface or direct-control logic inputs.

The MAX4814E is available in a 64-pin (10mm x 10mm) TQFP package and operates over the -40°C to +85°C extended temperature range.

Applications

Commercial/Industrial HDMI/DVI™ (Digital Visual Interface) Switch Boxes

High-End Consumer Switchers

AV Receivers with Switching

HDMI is a trademark of HDMI Licensing, LLC.
DVI is a trademark of Digital Display Working Group.

Features

- **+5V/Drain Switched**
- **HPD (Hot-Plug Detect) Switching**
- **DDC (Display Data Channel) Switching**
- **Direct Entry or I²C Control**
- **Low 1µA Quiescent Current**
- **±6kV Human Body Model (HBM) ESD Protection on Switch I/Os**
- **Companion IC to the MAX3845**
- **Provides I²C Control for the MAX3845**
- **Compact 64-Pin, 10mm x 10mm TQFP Package**
- **Optimized Layout to Support 4:4 or 2:8 Configuration with Two Devices**

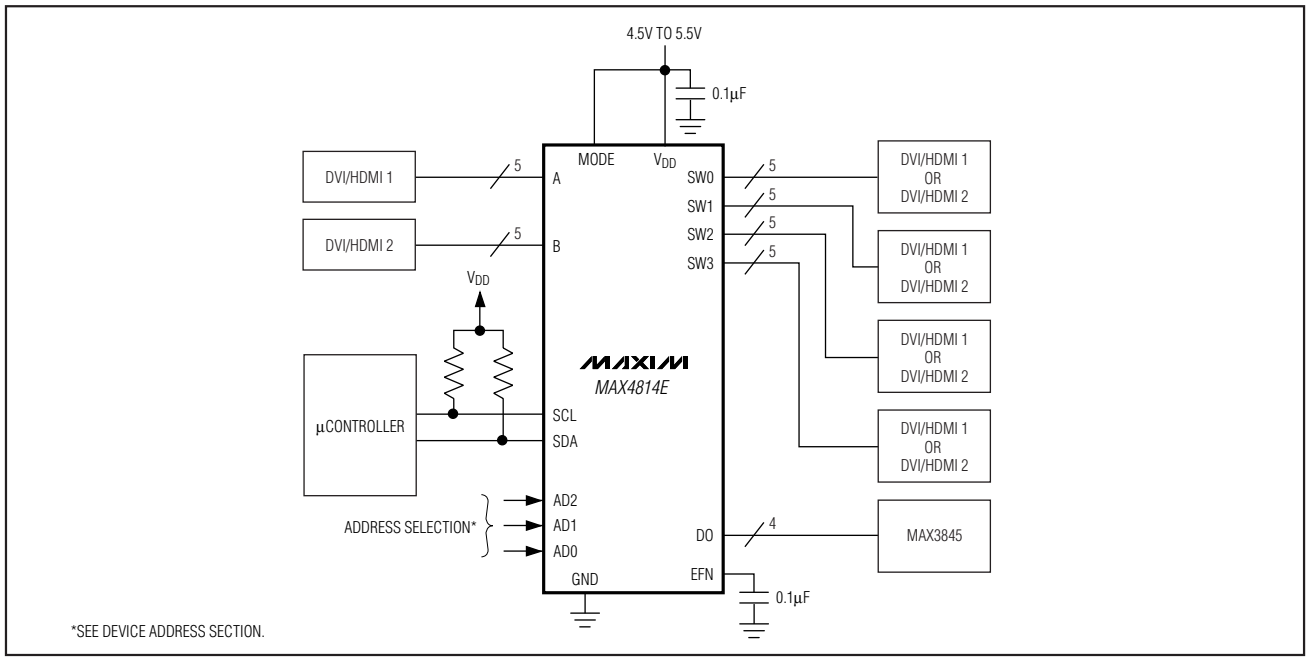
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	PKG CODE
MAX4814EECB+	-40°C to +85°C	64 TQFP-EP*	C64E-10

+Denotes a lead-free package.
**EP = Exposed paddle.*

Pin Configuration appears at end of data sheet.

Typical I²C Operating Circuit



DVI/HDMI 2:4 Low-Frequency Fanout Switch

ABSOLUTE MAXIMUM RATINGS

(Voltages referenced to GND. Note 1.)
V_{DD}, A_, B_, SW_, EFN.....-0.3V to +6.0V
All Other Pins (except GND).....-0.3V to V_{DD} + 0.3V
Continuous Current, A_, B_.....±60mA
Continuous Current, V_{DD} or GND.....±100mA

Continuous Power Dissipation (T_A = +70°C)
64-Pin TQFP (derate 31.3mW/°C above +70°C).....2508mW
Operating Temperature Range .....-40°C to +85°C
Junction Temperature.....+150°C
Storage Temperature Range .....-65°C to +150°C
Lead Temperature (soldering).....+300°C

Note 1: EFN must be either connected to V_{DD} or left unconnected. EFN must not be connected to ground.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{DD} = +5V ±10%, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C, V_{DD} = +5V. Note 2.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Power-Supply Voltage	V_{DD}		4.5	5	5.5	V
Power-Supply Current	I_{DD}	EFN = unconnected; all inputs = 0; all outputs high or low, no loads			10	µA
EFN Leakage Current	I_L	$V_{EFN} = V_{DD}$ - 0.2V	-2		+2	µA
LOGIC INPUTS (DA_, DB_, MODE, AD_)						
Input Low Voltage DA_, DB_	V_{IL}	MODE = 0V			0.8	V
Input High Voltage DA_, DB_	V_{IH}	MODE = 0V	2			V
Input-Voltage Hysteresis DA_, DB_	V_{HYST}	MODE = 0V		150		mV
Input Low Voltage AD_	V_{IL}	MODE = V_{DD}			0.8	V
Input High Voltage AD_	V_{IH}	MODE = V_{DD}	2			V
Input-Voltage Hysteresis AD_	V_{HYST}	MODE = V_{DD}		150		mV
Input Low Voltage MODE	V_{IL}				0.8	V
Input High Voltage MODE	V_{IH}		2			V
Input-Voltage Hysteresis MODE	V_{HYST}			150		mV
Input Leakage Current DA_, DB_	I_L	MODE = 0V			±1	µA
Input Leakage Current AD_	I_L	MODE = V_{DD}			±1	µA
Input Leakage Current MODE	I_L				±1	µA
LOGIC OUTPUTS DO_						
Output-Voltage Low	V_{OL}	MODE = V_{DD}, I_{SINK} = 30µA			0.5	V
Output-Voltage High	V_{OH}	MODE = V_{DD}, I_{SOURCE} = 26µA	2			V
Output Leakage Current	I_L	MODE = V_{DD}, output at high impedance, V_{IN} = 1.5V			±1	µA
Output Rise Time	t_R	V_{OUT} from 0.8V to 2.2V, C_{LOAD} = 10pF		600		ns
Output Short-Circuit Current	I_{SC}	I_{SOURCE}			-1	mA
		I_{SINK}			+3	

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ELECTRICAL CHARACTERISTICS (continued)

(V_{DD} = +5V ±10%, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C, V_{DD} = +5V. Note 2.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG SWITCHES						
On-Resistance Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	R_{ON}	V_{IN} = 2.5V, I_{IN} = ±10mA		12		Ω
On-Resistance-Flatness Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	R_{FLAT}	V_{IN} = 0.8V, 2.5V, 3.7V		2.5		Ω
On-Channel -3dB Bandwidth Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	BW	R_S = R_L = 50Ω, C_L = 35pF, Figure 1		190		MHz
Off-Isolation Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	V_{ISO}	R_S = R_L = 50Ω, f = 1MHz, Figure 1		65		dB
Crosstalk Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	V_{CT}	R_S = R_L = 50Ω, f = 1MHz, Figure 1		75		dB
On-Capacitance Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	C_{ON}	V_{DD} = 4.5V, f = 1MHz, Figure 2		37		pF
Off-Capacitance Standard Switches: A[1], A[2], A[3], B[1], B[2], B[3]	C_{OFF}	V_{DD} = 4.5V, f = 1MHz, Figure 2		15		pF
Charge Injection	Q	V_{GEN} = 1.5V, R_{GEN} = 0Ω, C_L = 100pF, Figure 3		13		pC
On-Resistance +5V/Drain: A[0], A[4], B[0], B[4]	R_{ON}	V_{DD} = 4.5V, V_{IN} = 0V or V_{DD}		3		Ω
Switch Leakage Current	I_L				±10	µA
I^2C SPECIFICATIONS (SDA, SCL, MODE = V_{DD})						
Input Low Voltage	V_{IL}				0.8	V
Input High Voltage	V_{IH}		2.4			V
Input-Voltage Hysteresis	V_{HYST}			450		mV
Input Leakage Current	I_L				±1	µA
Output-Voltage Low SDA	V_{OL}	I_{SINK} = 3mA			0.4	V
TIMING CHARACTERISTICS (Figure 4), MODE = V_{DD}						
Serial Clock Frequency	f_{SCL}	V_{DD} = 4.5V	100	400		kHz
Hold Time (Repeated) START Condition (after this period the first clock pulse is generated)	$t_{HD,STA}$	f_{SCL} = 100kHz	4			µs
Low Period of the SCL Clock	t_{LOW}	f_{SCL} = 100kHz	4.7			µs

DVI/HDMI 2:4 Low-Frequency Fanout Switch

ELECTRICAL CHARACTERISTICS (continued)

(V_{DD} = +5V ±10%, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C, V_{DD} = +5V. Note 2.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
High Period of the SCL Clock	t_{HIGH}	f_{SCL} = 100kHz	4			µs
Setup Time for a Repeated START Condition	$t_{SU,STA}$	f_{SCL} = 100kHz	4.7			µs
Data Hold Time	$t_{HD,DAT}$	f_{SCL} = 100kHz	25			µs
Data Setup Time	$t_{SU,DAT}$	f_{SCL} = 100kHz	250			ns
ESD PROTECTION (HUMAN BODY MODEL)						
SW_, A_, B_	ESD	Referenced to GND		±6		kV
All Other I/Os				±2		

Note 2: Limits at T_A = -40°C are guaranteed by design.

DVI/HDMI 2:4 Low-Frequency Fanout Switch

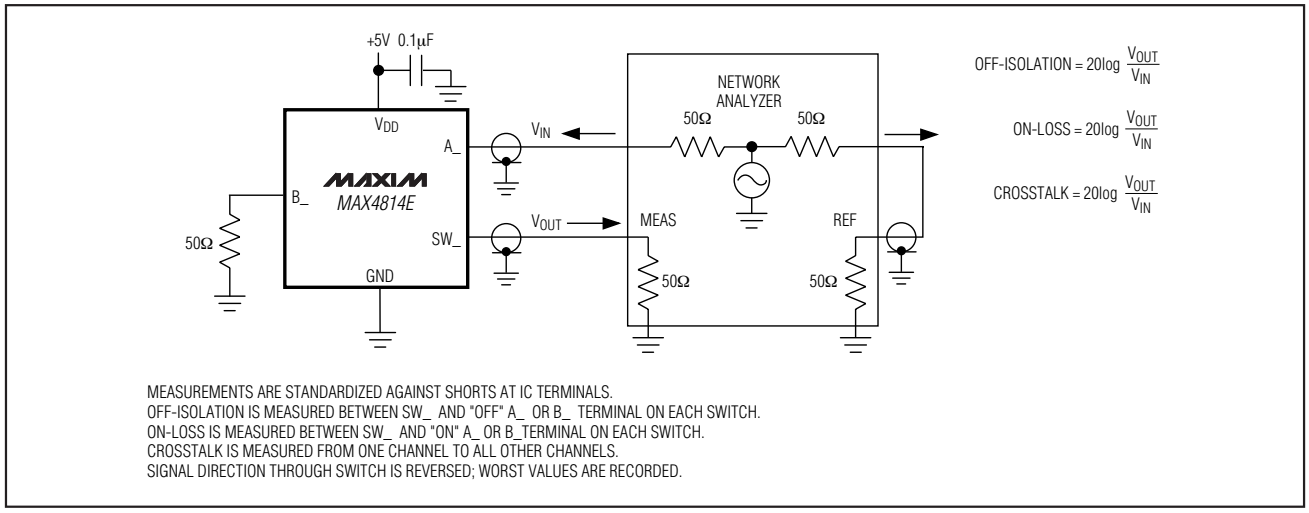


Figure 1. On-Loss, Off-Isolation, and Crosstalk

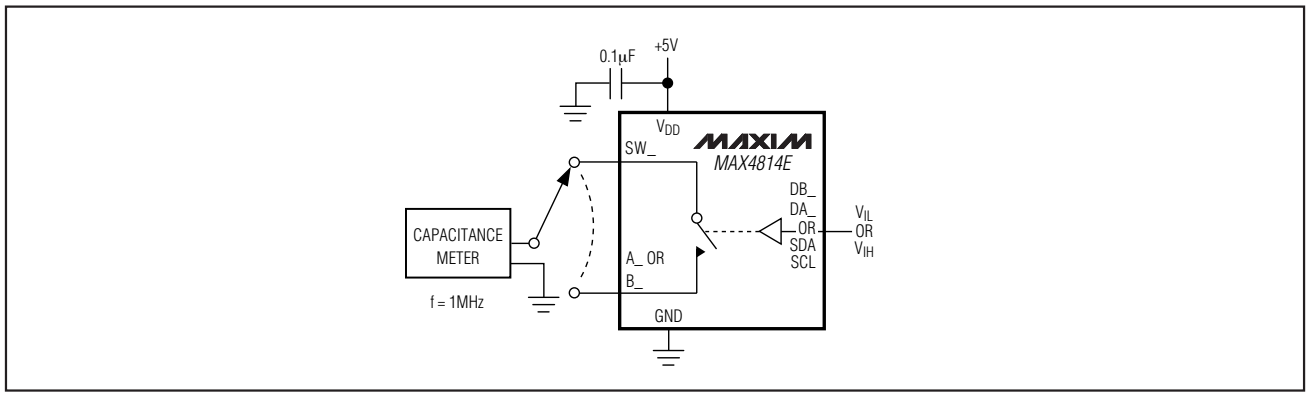


Figure 2. Channel Off-/On-Capacitance

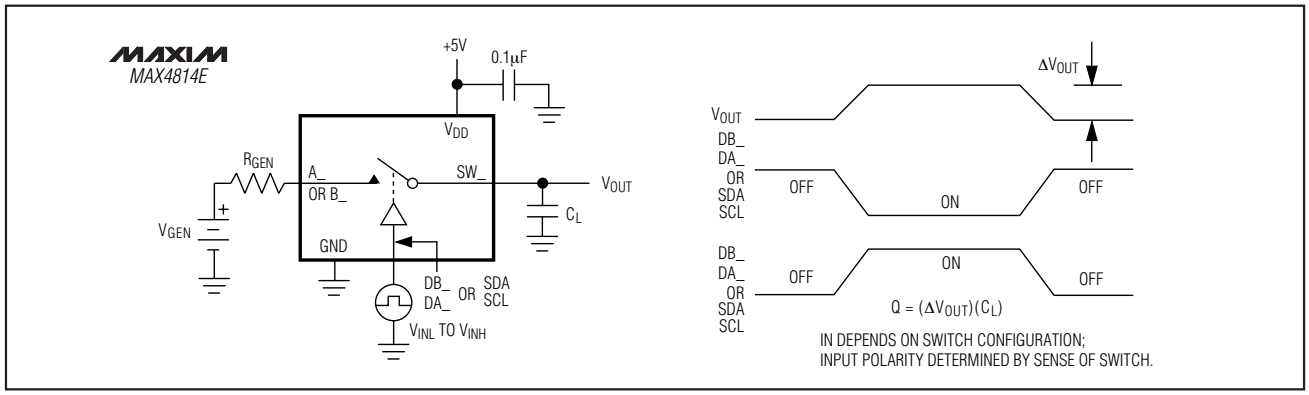


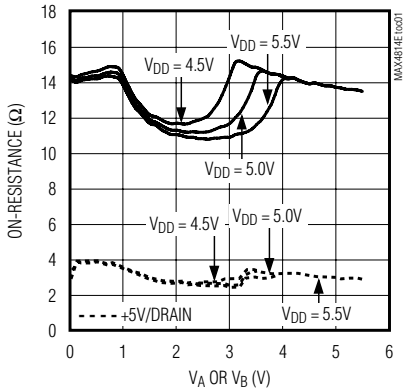
Figure 3. Charge Injection

DVI/HDMI 2:4 Low-Frequency Fanout Switch

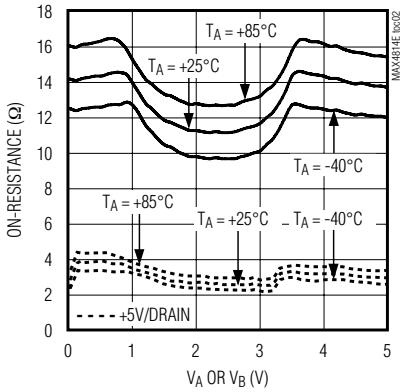
Typical Operating Characteristics

(V_{DD} = +5V, T_A = +25°C, unless otherwise noted.)

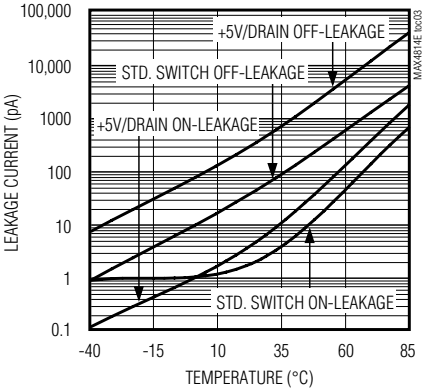
ON-RESISTANCE vs. V_A OR V_B



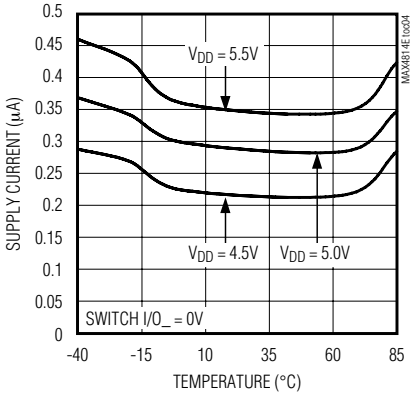
ON-RESISTANCE vs. V_A OR V_B



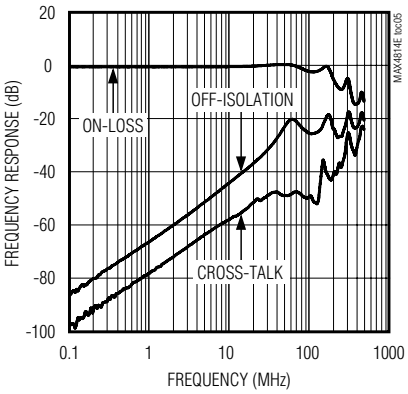
LEAKAGE CURRENT vs. TEMPERATURE



SUPPLY CURRENT vs. TEMPERATURE



FREQUENCY RESPONSE



DVI/HDMI 2:4 Low-Frequency Fanout Switch

Pin Description

PIN	NAME	FUNCTION
1, 16, 24, 25, 33, 48, 56, 57	GND	Ground. Must connect all GND pins together.
2, 15, 34	I.C.	Internally Connected. Leave I.C. unconnected
3	A[0]	Switch A I/O 0. A[0] has a 3Ω (typ) resistance to switch 5V or drain.
4	A[1]	Switch A I/O 1. A[1] has a 12Ω (typ) resistance to switch data.
5	A[2]	Switch A I/O 2. A[2] has a 12Ω (typ) resistance to switch data.
6	A[3]	Switch A I/O 3. A[3] has a 12Ω (typ) resistance to switch data.
7	A[4]	Switch A I/O 4. A[4] has a 3Ω (typ) resistance to switch 5V or drain.
8, 9, 17, 32, 40, 41, 49, 64	V_{DD}	Positive-Supply Voltage Input. Connect V_{DD} to a +5V supply voltage. Bypass V_{DD} to GND with a 0.1µF capacitor. Must connect all V_{DD} pins together.
10	B[0]	Switch B I/O 0. B[0] has a 3Ω (typ) resistance to switch 5V or drain.
11	B[1]	Switch B I/O 1. B[1] has a 12Ω (typ) resistance to switch data.
12	B[2]	Switch B I/O 2. B[2] has a 12Ω (typ) resistance to switch data.
13	B[3]	Switch B I/O 3. B[3] has a 12Ω (typ) resistance to switch data.
14	B[4]	Switch B I/O 4. B[4] has a 3Ω (typ) resistance to switch 5V or drain.
18	MODE	MODE Selection Input. Connect MODE to V_{DD} (MODE = 1) to select I^2C control mode. Connect MODE to GND (MODE = 0) to select direct-control mode.
19	SDA	I^2C-Compatible Serial Data I/O
20	SCL	I^2C-Compatible Serial Clock Input
21	AD0	Programmable I^2C Address Bit. AD[0] sets the I^2C address of the device. User-selectable device address bit, LSB, LSB+1, MSB (see Figure 5).
22	AD1	Programmable I^2C Address Bit. AD[1] sets the I^2C address of the device. User-selectable device address bit, LSB, LSB+1, MSB (see Figure 5).
23	AD2	Programmable I^2C Address Bit. AD[2] sets the I^2C address of the device. User-selectable device address bit, LSB, LSB+1, MSB (see Figure 5).
26	SW3[4]	Switch 3 I/O 4
27	SW3[3]	Switch 3 I/O 3
28	SW3[2]	Switch 3 I/O 2
29	SW3[1]	Switch 3 I/O 1
30	SW3[0]	Switch 3 I/O 0
31, 50	EFN	ESD Protection. Connect EFN with an external 0.1µF capacitor to GND for ±15kV ESD HBM protection. The capacitor from EFN to GND provides an additional discharge path for the ESD energy.
35	SW2[4]	Switch 2 I/O 4
36	SW2[3]	Switch 2 I/O 3
37	SW2[2]	Switch 2 I/O 2
38	SW2[1]	Switch 2 I/O 1
39	SW2[0]	Switch 2 I/O 0
42	SW1[4]	Switch 1 I/O 4
43	SW1[3]	Switch 1 I/O 3
44	SW1[2]	Switch 1 I/O 2

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Pin Description (continued)

PIN	NAME	FUNCTION
45	SW1[1]	Switch 1 I/O 1
46	SW1[0]	Switch 1 I/O 0
47	N.C.	No Connection. Not internally connected.
51	SW0[4]	Switch 0 I/O 4
52	SW0[3]	Switch 0 I/O 3
53	SW0[2]	Switch 0 I/O 2
54	SW0[1]	Switch 0 I/O 1
55	SW0[0]	Switch 0 I/O 0
58	DA0/DO0	Direct-Control Bit I/O. In mode 0, DA0/DO0 is set as an input, DA0, to control switch connections. In mode 1, DA0/DO0 is set as an output, DO0. The output bits are used to drive the MAX3845.
59	DA1/DO1	Direct-Control Bit I/O. In mode 0, DA1/DO1 is set as an input, DA1, to control switch connections. In mode 1, DA1/DO1 is set as an output, DO1. The output bits are used to drive the MAX3845.
60	DA2/DO2	Direct-Control Bit I/O. In mode 0 DA2/DO2 is set as an input, DA2, to control switch connections. In mode 1, DA2/DO2 is set as an output, DO2. The output bits are used to drive the MAX3845.
61	DB0/DO3	Direct-Control Bit I/O. In mode 0 DB0/DO3 is set as an input, DB0, to control switch connections. In mode 1, DB0/DO3 is set as an output, DO3. The output bits are used to drive the MAX3845.
62	DB1	Direct-Control Bit I/O. In mode 0, DB1 is set as an input. In mode 1, DB1 is high impedance.
63	DB2	Direct-Control Bit I/O. In mode 0, DB2 is set as an input. In mode 1, DB2 is high impedance.
EP	EP	Exposed Pad. Connect exposed pad to ground. For enhanced thermal dissipation, connect EP to a copper area as large as possible. Do not use EP as a sole ground connection.

Detailed Description

The MAX4814E provides routing for low-frequency DVI/HDMI signals. The MAX4814E is a bidirectional 2:4 DVI/HDMI switch. Each switch consists of five single-pole/single-throw (SPST) channels. The channels have a low 3Ω (typ) on-resistance to route +5V and drain, and three channels to route data. Channels A0, A4, B0, B4, SW_0, and SW_4 have a 3Ω (typ) on-resistance to route +5V and drain, and the remaining channels A1–A3, B1–B3, SL0_3, and SW_1 have a 12Ω (typ) on-resistance to route data. The device features a mode input to control the device using direct-control logic inputs or an I^2C interface. Connect MODE to GND to control the device using the direct-control bits. Connect MODE to V_{DD} to control the device using I^2C. In I^2C mode, the MAX4814E controls the MAX3845 (see Figure 5).

Analog Signal Levels

Signal inputs over the full voltage range (0V to V_{DD}) are passed through the switch with minimal change in on-resistance (see the *Typical Operating Characteristics*). The switches are bidirectional. Therefore, switch A_, switch B_, and switch SW_ can be either inputs or outputs.

Switch Control

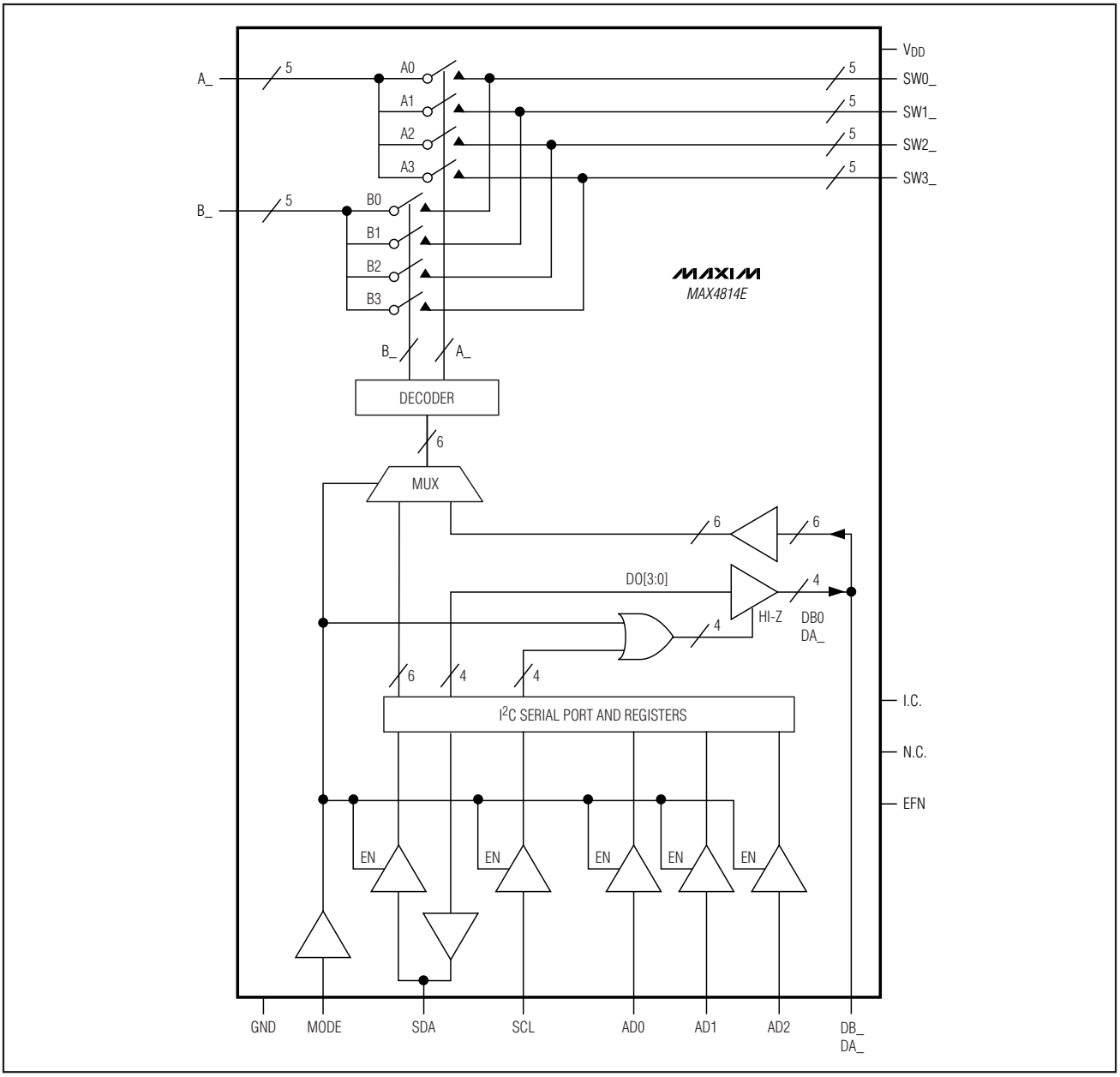
The MAX4814E features a mode input to control the device through either an I^2C interface or through direct-control logic inputs. Connect MODE to GND (mode 0) to control the device using the direct-control inputs DA_ and DB_ (see Table 1 and Figure 6). Connect MODE to V_{DD} (mode 1) to control the device using the I^2C interface.

Direct Control Method (Mode 0)

In mode 0, DA0/DO0 becomes input DA0, DA1/DO1

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Functional Diagram



becomes input DA1, DA2/DO2 becomes input DA2, and DB0/DO3 becomes input DB0. Inputs DB1 and DB2 are enabled.

In mode 0, the direct-control inputs DA_ and DB_ are used to control the connection of the switches. DA2 is used as the enable for switch A, and DB2 is used as the enable for switch B. Connecting DA2 to V_{DD} enables switch A, and connecting DA2 to GND disables switch A. Connecting DB2 to V_{DD} enables switch B, and connecting DB2 to GND disables switch B. Inputs DA0 and

DVI/HDMI 2:4 Low-Frequency Fanout Switch

DA1 select the connections of switch A to switch SW_ and inputs DB0 and DB1. Select the connections of switch B to SW_. See Table 3a for the pin configuration and Table 3b for a complete summary.

I²C Interface Method (Mode 1)

In mode 1, the switch connections are controlled through the I²C interface. Inputs SDA and SCL program registers R0 and R1. Register R0, bits [7 to 2], select the connection of switch A and switch B to switch SW_ (see the *I²C Registers and Bit Descriptions* section).

The bits of register R1 transfer data to the output DO_. The data on output DO_ is used to communicate with the MAX3845. In mode 1, DA0/DO0 becomes output DO0, DA1/DO1 becomes output DO1, DA2/DO2 becomes output DO2, and DB0/DO3 becomes output DO3. DB1 and DB2 are high impedance. See Table 3a for the pin configuration. See Table 4 for register R1 to DO_ output mapping.

_I²C Registers and Bit Descriptions

Two internal registers (RO and R1) program the MAX4814E. Table 2 lists both registers, their addresses, and power-up default states. Both registers are read/write registers.

In register R0, bit BAEN is used as the enable for switch A, and bit BBEN is used as the enable for switch B. Writing 1 to bit BAEN enables switch A; and writing 0 to bit BAEN disables switch A. Writing 1 to bit BBEN enables switch B, and writing 0 to bit BBEN disables switch B. BASEL1 and BASEL0 select the connections of switch A to switch SW_, while BBSEL1 and BBSEL0 select the connections of switch B to switch SW_, as summarized in Table 6.

I²C Register R0 Two LSB Bits

The two LSBs are hard coded as 00. Register R0 ignores any value written to the two LSBs; anytime register R0 is read the hard-coded values are returned.

Bank A Enable (BAEN) and Bank B Enable (BBEN) Bits

1 = Enable
0 = Disable

Bank A Select (BASEL1/BASEL0) and Bank B Select (BBSEL1/BBSEL0) Bits

Bits BASEL1 and BASEL0 select the switch SW_ that switch A is connected to. Bits BBSEL1 and BBSEL0 select the switch SW_ that switch B is connected to (see Table 6).

Power-On Default States

When power is applied to the MAX4814E internal power-on reset (POR), circuitry sets registers R0 and R1 to their default states. Register R0 is set to all zeros, or 00h, and register R1 is set to 10101010, or AAh, as shown in Table 2.

Having all zeros in register R0 disables both banks A and B; see Table 6 for register R0 to switch mapping. Setting register R1 to AAh forces the outputs at DO_ to be high impedance.

Note: The output, DO_ is used to communicate with the MAX3845 when the MAX4814E is being used without its companion. The MAX3845 and the MAX4814E use the I²C interface (MODE = 1). All DO_ outputs need to be connected through a 10kΩ resistor to GND.

Table 1. Mode Configuration

INPUT PIN MODE	OPERATION
0	Puts the device in mode 0. The direct-control inputs DA_ and DB_ control the switches.
1	Puts the device in mode 1. The switches are controlled by the I²C interface. DO_ becomes an active output. Inputs DB1 and DB2 are high impedance.

Table 2. I²C Register Map

REGISTER	BIT								ADDRESS	POWER-UP	
	7	6	5	4	3	2	1	0		BINARY	HEX
R0	BBEN	BBSEL1	BBSEL0	BAEN	BASEL1	BASEL0	X	X	0x00	0000 0000	00
R1	DO3 High Impedance	DO3 Data	DO2 High Impedance	DO2 Data	DO1 High Impedance	DO1 Data	DO0 High Impedance	DO0 Data	0x01	1010 1010	AA

X = Hardwired code, not programmable by user.

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Table 3a. Input/Output Configurations for DA_, DB_, and DO_

MODE	PIN CONFIGURATION					
	DA0/DO0	DA1/DO1	DA2/DO2	DB0/DO3	DB1	DB2
0	DA0, Input	DA1, Input	DA2, Input	DB0, Input	DB1, Input	DB2, Input
1	DO0, Output	DO1, Output	DO2, Output	DO3, Output	High Impedance	High Impedance

Table 3b. Mode 0 Direct-Control Configurations

PIN CONNECTION DA2	OPERATION
0	Bank A switches are disabled
1	Bank A switches are enabled. Switch A connections depend on the DA0 and DA1 inputs.

PIN CONNECTION DB2	OPERATION
0	Bank B switches are disabled
1	Bank B switches are enabled. Switch B connections depend on the DB0 and DB1 inputs.

PIN CONNECTION				OPERATION	
DB1	DB0	DA1	DA0		
0	0	0	0	Connect A to SW0	B is high impedance
0	0	0	1	Connect A to SW1	Connect B to SW0
0	0	1	0	Connect A to SW2	Connect B to SW0
0	0	1	1	Connect A to SW3	Connect B to SW0
0	1	0	0	Connect A to SW0	Connect B to SW1
0	1	0	1	Connect A to SW1	B is high impedance
0	1	1	0	Connect A to SW2	Connect B to SW1
0	1	1	1	Connect A to SW3	Connect B to SW1
1	0	0	0	Connect A to SW0	Connect B to SW2
1	0	0	1	Connect A to SW1	Connect B to SW2
1	0	1	0	Connect A to SW2	B is high impedance
1	0	1	1	Connect A to SW3	Connect B to SW2
1	1	0	0	Connect A to SW0	Connect B to SW3
1	1	0	1	Connect A to SW1	Connect B to SW3
1	1	1	0	Connect A to SW2	Connect B to SW3
1	1	1	1	Connect A to SW3	B is high impedance

Note: *When switch A and switch B are connected to the same SW_, switch A takes precedence and switch B is high impedance.*

I²C Interface

The MAX4814E features an I²C interface using a repeated start. The MAX4814E I²C interface refers to the I²C bus specification (version 2.1, Jan 2000).

Device Address

The MAX4814E has selectable device addresses through external inputs. The slave address consists of four fixed bits (B7–B4, set to 0111) followed by three pin-programmable bits (AD2–AD0), as shown on Table 7.

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Table 4. I²C Register R1 (0X01) to DO_ Mapping

PIN	REGISTER R1 (0x01)								OUTPUT PIN CONFIGURATION	
MODE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0		
1	—	—	—	—	—	—	0	0	DO0	0
1	—	—	—	—	—	—	0	1	DO0	1
1	—	—	—	—	—	—	1	X	DO0	Hi-Z
1	—	—	—	—	0	0	—	—	DO1	0
1	—	—	—	—	0	1	—	—	DO1	1
1	—	—	—	—	1	X	—	—	DO1	Hi-Z
1	—	—	0	0	—	—	—	—	DO2	0
1	—	—	0	1	—	—	—	—	DO2	1
1	—	—	1	X	—	—	—	—	DO2	Hi-Z
1	0	0	—	—	—	—	—	—	DO3	0
1	0	1	—	—	—	—	—	—	DO3	1
1	1	X	—	—	—	—	—	—	DO3	Hi-Z

X = Don't care.

Table 5. I²C Register R0 (0x00)

REGISTER R0 (0x00)							
BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
BBEN	BBSEL1	BBSEL0	BAEN	BASEL1	BASEL0	X	X

X = Hardwired, not programmed by user.

For example: If AD0, AD1, and AD2 are hardwired to ground, then the complete address is 0111000. The full address is defined as the seven most significant bits followed by the read/write bit. Set the read/write bit to 1 to configure the MAX4814E to read mode. Set the read/write bit to 0 to configure the MAX4814E to write mode. The address is the first byte of information sent to the MAX4814E after the START condition.

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Applications Information

ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. Switch A, switch B, and switch SW_ are further protected against static electricity. Maxim's engineers have developed state-of-the-art structures to protect these pins against ESD up to ±6kV without damage. The ESD structures withstand high ESD in normal operation, and when the device is powered down. ESD protection can be tested in various ways. The ESD protection of switch A, switch B, and switch SW_ are characterized for ±6kV (Human Body Model) using the MIL-STD-883.

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model

Figure 7 shows the Human Body Model, and Figure 8 shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest that is then discharged into the test device through a 1.5kΩ resistor.

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Table 6. Switch Selection Truth Table

DA_, DB_ INPUTS/REGISTER R0 BITS						SWITCH A AND B TO SW_ CONNECTIONS							
DB2/ BBEN	DB1/ BBSEL1	DB0/ BBSEL0	DA2/ BAEN	DA1/ BASEL1	DA0/ BASEL0	B TO SW3	B TO SW2	B TO SW1	B TO SW0	A TO SW3	A TO SW2	A TO SW1	A TO SW0
0	X	X	0	X	X	—	—	—	—	—	—	—	—
0	X	X	1	0	0	—	—	—	—	—	—	—	1
0	X	X	1	0	1	—	—	—	—	—	—	1	—
0	X	X	1	1	0	—	—	—	—	—	1	—	—
0	X	X	1	1	1	—	—	—	—	1	—	—	—
1	0	0	0	X	X	—	—	—	1	—	—	—	—
1	0	0	1	0	0	—	—	—	0	—	—	—	1
1	0	0	1	0	1	—	—	—	1	—	—	1	—
1	0	0	1	1	0	—	—	—	1	—	1	—	—
1	0	0	1	1	1	—	—	—	1	1	—	—	—
1	0	1	0	X	X	—	—	1	—	—	—	—	—
1	0	1	1	0	0	—	—	1	—	—	—	—	1
1	0	1	1	0	1	—	—	0	—	—	—	1	—
1	0	1	1	1	0	—	—	1	—	—	1	—	—
1	0	1	1	1	1	—	—	1	—	1	—	—	—
1	1	0	0	X	X	—	1	—	—	—	—	—	—
1	1	0	1	0	0	—	1	—	—	—	—	—	1
1	1	0	1	0	1	—	1	—	—	—	—	1	—
1	1	0	1	1	0	—	0	—	—	—	1	—	—
1	1	0	1	1	1	—	1	—	—	1	—	—	—
1	1	1	0	X	X	1	—	—	—	—	—	—	—
1	1	1	1	0	0	1	—	—	—	—	—	—	1
1	1	1	1	0	1	1	—	—	—	—	—	1	—
1	1	1	1	1	0	1	—	—	—	—	1	—	—
1	1	1	1	1	1	0	—	—	—	1	—	—	—

— = Denotes no connection.
1 = Denotes switch connection.
0 = Denotes switch B is high impedance.
X = Don't care.

Table 7. MAX4814E Device Address

B7	B6	B5	B4	B3	B2	B1	B0
0	1	1	1	AD2	AD1	AD0	R/$\overline{W}$
Fixed				User Selected			—

Power-Supply Biasing and Sequencing

Proper power-supply sequencing is recommended for all CMOS devices. Do not exceed the absolute maximum ratings, since stresses beyond the listed ratings can cause permanent damage to the device. Always sequence V_{DD} on first, followed by the switch inputs and the logic inputs. Bypass at least one V_{DD} input to ground with a 0.1µF capacitor as close as possible to the device. Use the smallest physical size possible for optimal performance.

DVI/HDMI 2:4 Low-Frequency Fanout Switch

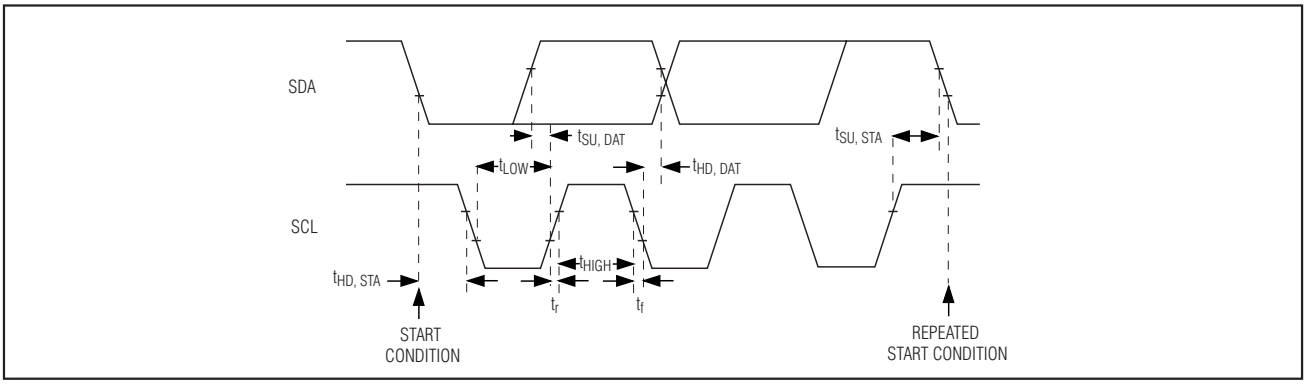


Figure 4. 2-Wire Interface Timing Diagram

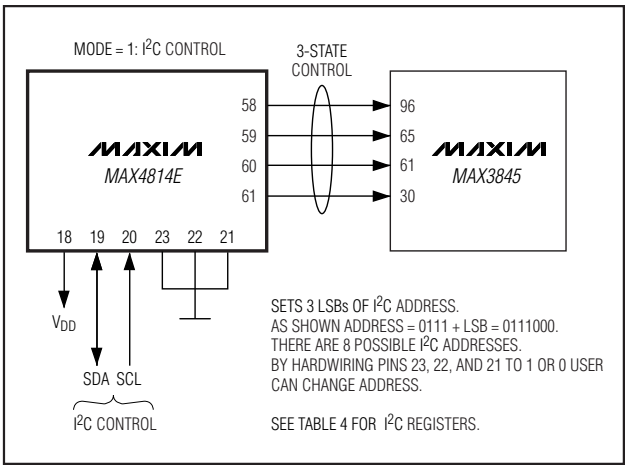


Figure 5. Mode 1: I²C Control

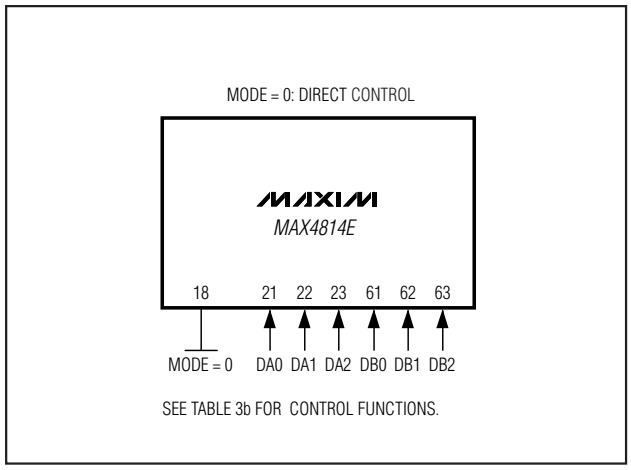


Figure 6. Mode 0: Direct Control

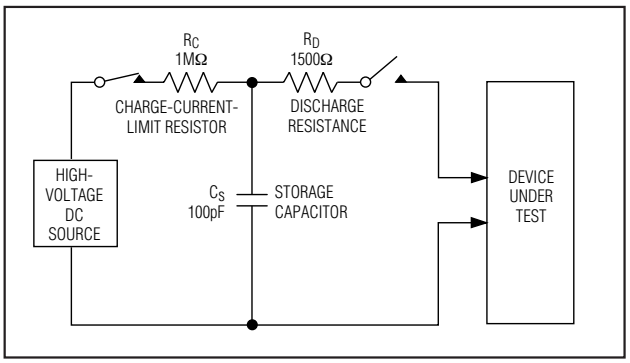


Figure 7. Human Body ESD Test Model

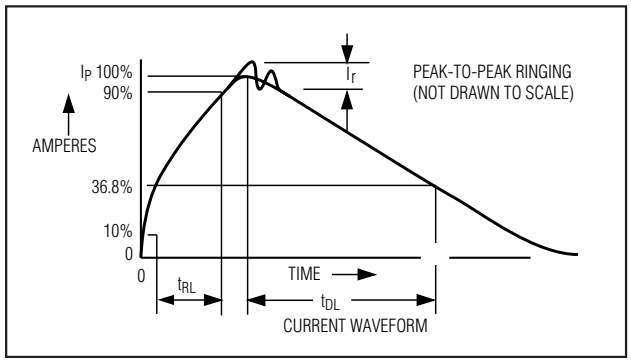
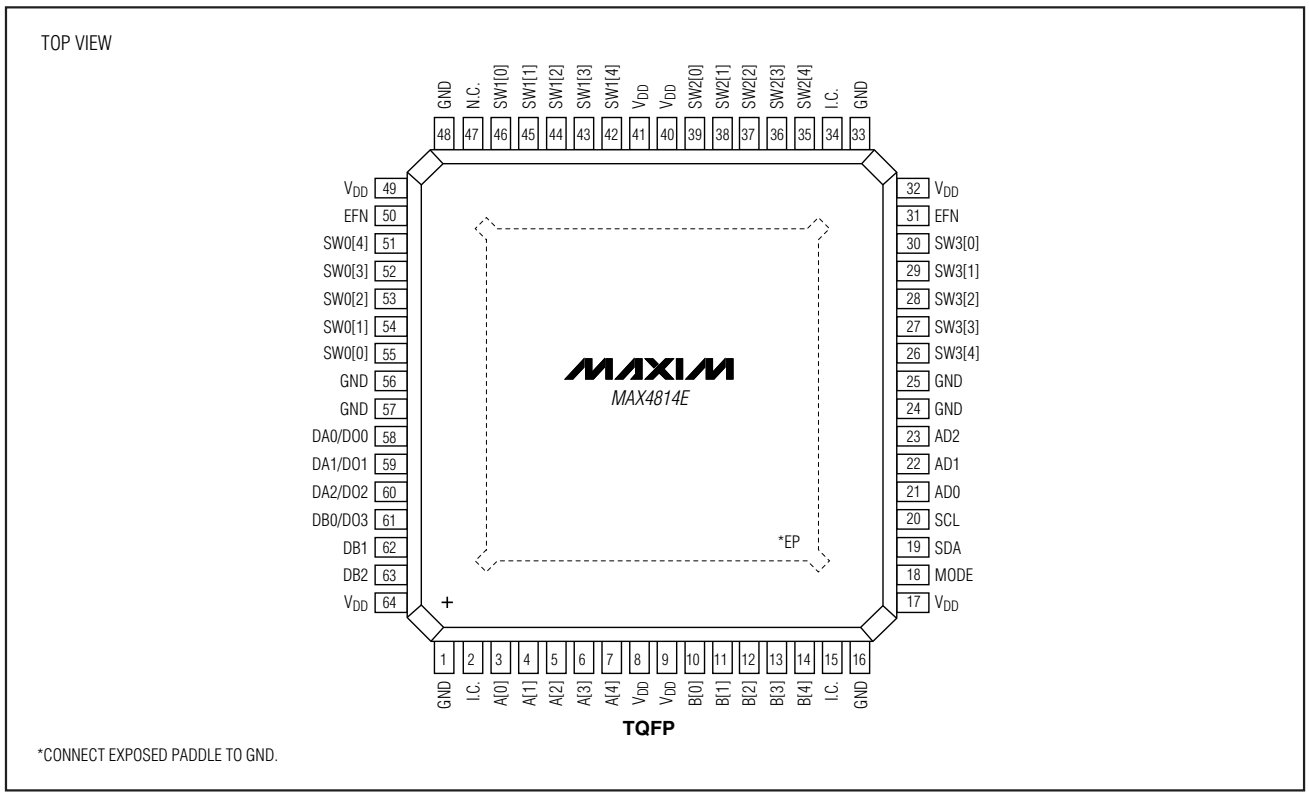


Figure 8. Human Body Current Waveform

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Pin Configuration



It is also recommended to bypass more than one V_{DD} input. A good strategy is to bypass one V_{DD} input with a 0.1µF capacitor and at least a second V_{DD} input with a 1nF to 10nF capacitor (use a 0603 or smaller physical size ceramic capacitor).

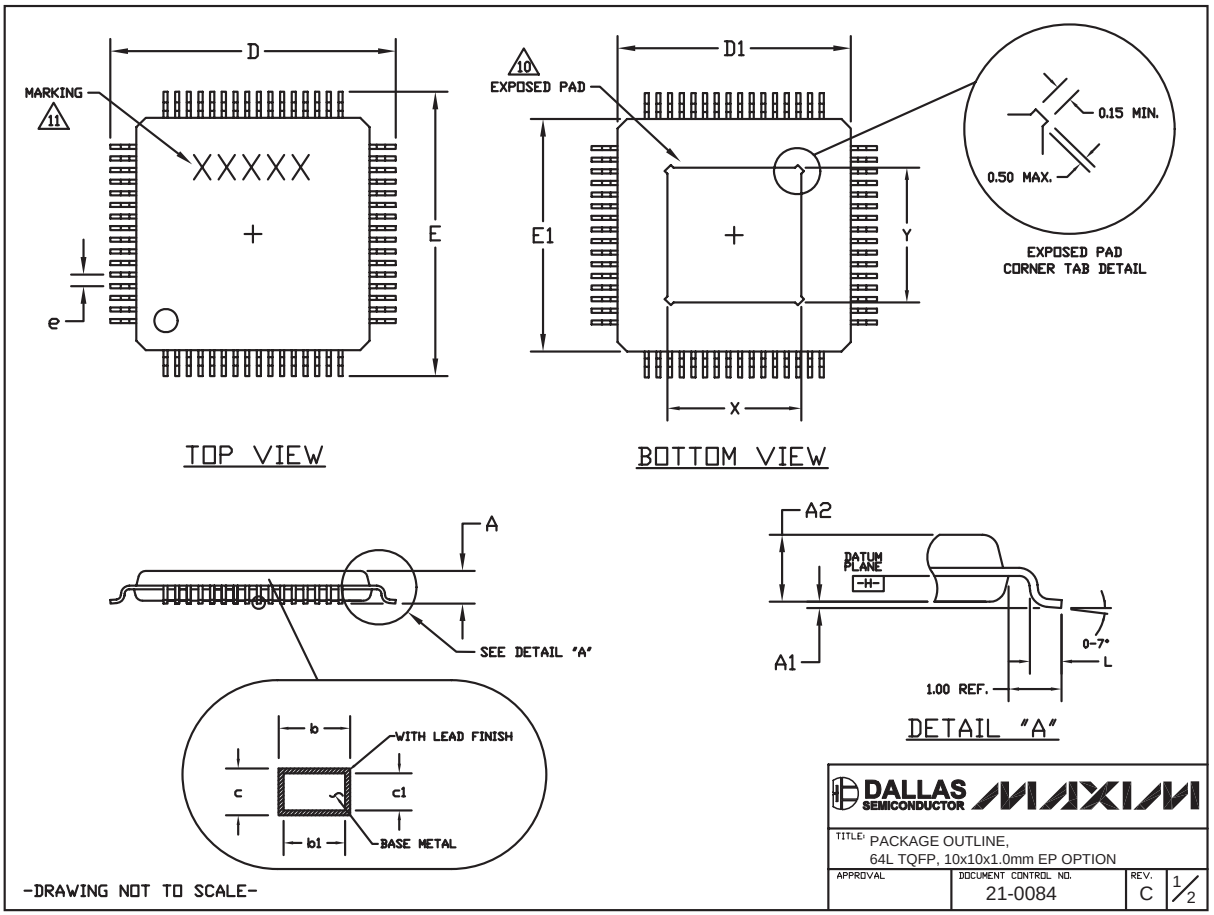
Chip Information

PROCESS: BiCMOS

DVI/HDMI 2:4 Low-Frequency Fanout Switch

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



DVI/HDMI 2:4 Low-Frequency Fanout Switch

Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

NOTES:
1. ALL DIMENSIONS AND TOLERANCING CONFORM TO ANSI Y14.5-1982.
2. DATUM PLANE -H- IS LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 MM ON D1 AND E1 DIMENSIONS.
4. THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. CONTROLLING DIMENSION: MILLIMETER.
7. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-026, VARIATION ACD.
8. LEADS SHALL BE COPLANAR WITHIN .004 INCH.
9. EXPOSED DIE PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 2 MILS (.05 MM).
10. DIMENSIONS X & Y APPLY TO EXPOSED PAD (EP) VERSIONS ONLY. SEE INDIVIDUAL PRODUCT DATASHEET TO DETERMINE IF A PRODUCT USES EXPOSED PAD PACKAGE.
11. MARKING SHOWN IS FOR PACKAGE ORIENTATION REFERENCE ONLY.

SYMBOL	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS	
	ACD-HD	
	MIN.	MAX.
A		1.20
A_1	0.05	0.15
A_2	0.95	1.05
D	11.80	12.20
D_1	9.80	10.20
E	11.80	12.20
E_1	9.80	10.20
L	0.45	0.75
N	64	
e	0.50 BSC.	
b	0.17	0.27
b1	0.17	0.23
c	0.09	0.20
c1	0.09	0.16
X	4.70	5.30
Y	4.70	5.30

-DRAWING NOT TO SCALE-

DALLAS SEMICONDUCTOR MAXIM

TITLE: PACKAGE OUTLINE, 64L TQFP, 10x10x1.0mm EP OPTION

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0084	C	2/2